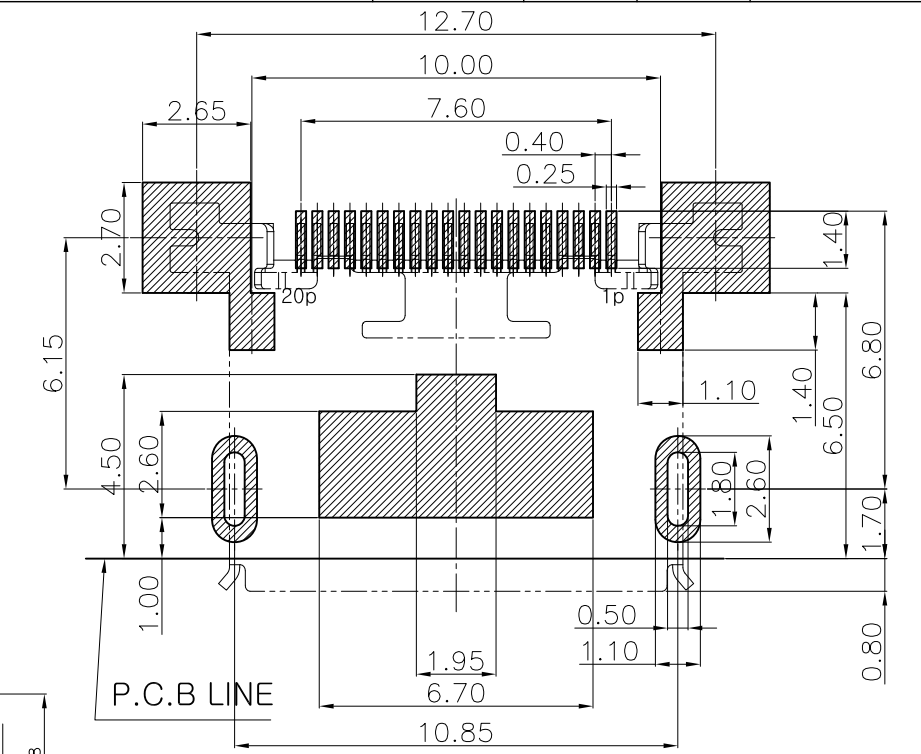
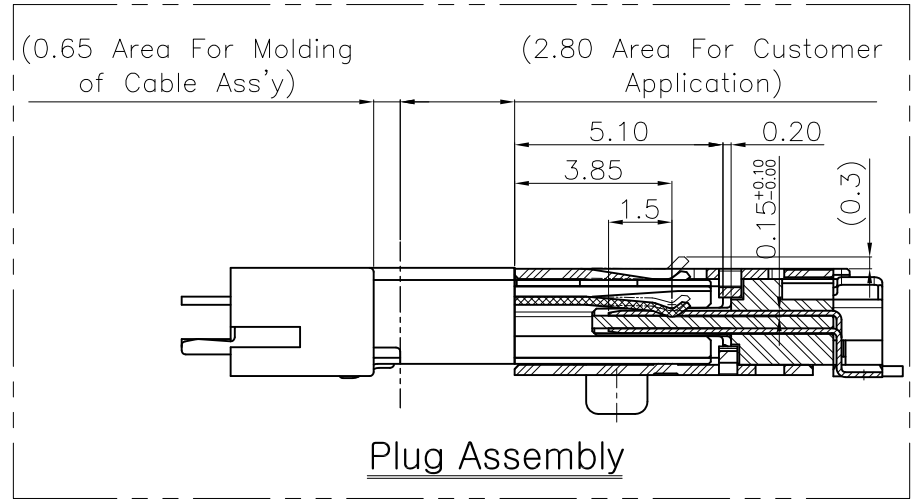
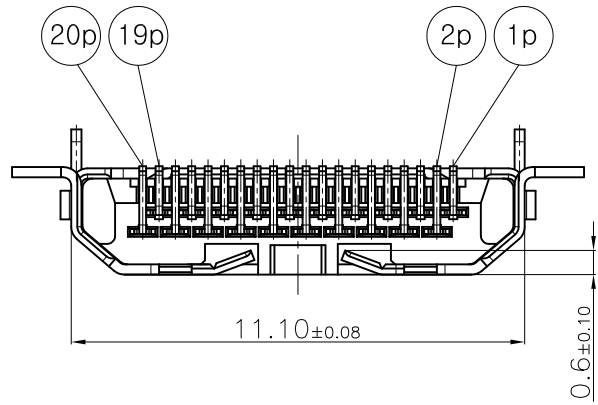
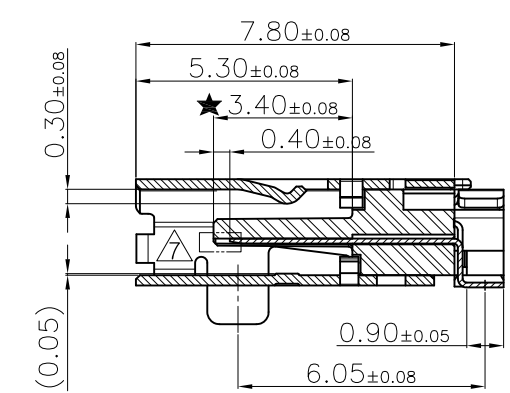
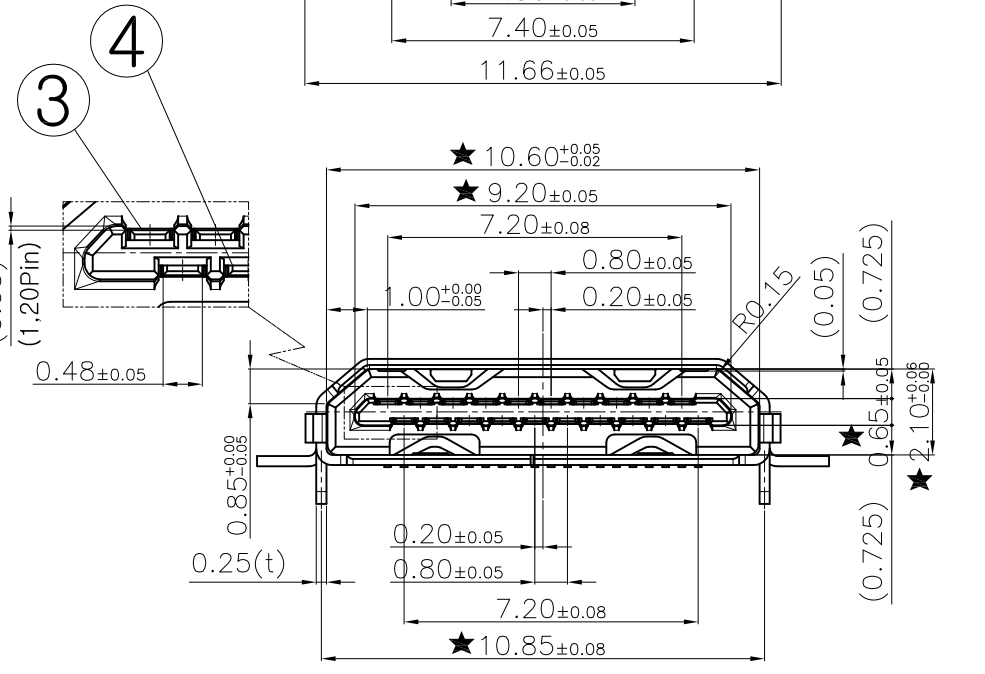
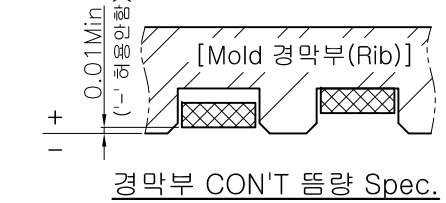
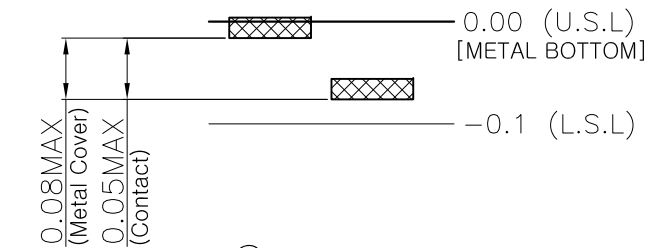
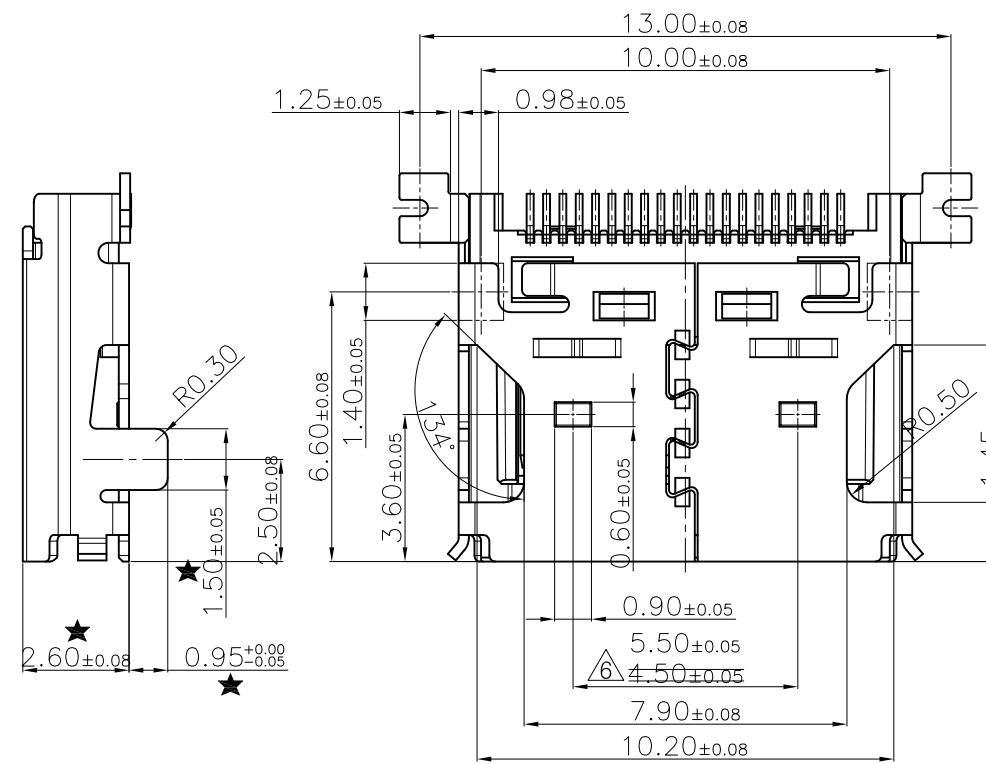
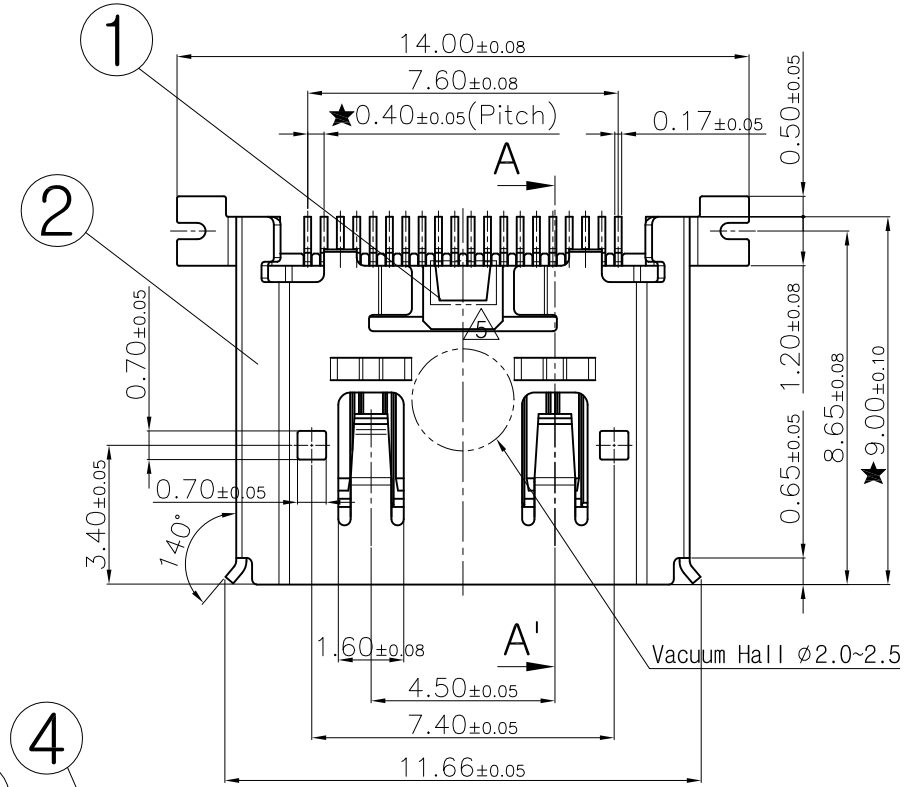


Rev No.	Description of Revision	Date	Name	Approved	ECN No.
5 X 1	생산성 향상을 위한 Housing 살빼기 추가	2008.05.06	M.G. Son		080506-01
6 X 1	Plug 조립성 개선	2008.11.06	M.G. Son	K.Y. Choi	081106-03
7 X 1	Housing Chamfer 삭제(핀밀링방지)	2008.12.17	M.G. Son	K.Y. Choi	081027-01
8 X 3	Contact 원소재, Housing Resin 변경	2009.01.20	S.C. LEE	K.Y. Choi	090416-02



PCB Lay Out
General Tolerance: ±0.05



Section A-A'

※ Note
1. Plating
1) Contact -Contact Area :Au 0.3μm Min over Ni 1~5μm
-Lead Area :Au 0.05μm over Ni 0.2~3μm
2) METAL COVER : Ni 1~5μm(無光)
2. ★ = C.T.Q

No	Descriptions	Material	Finish	Remarks
4	Contact "B"	8 Copper Alloy(C7025)		Note. 1 0.12t
3	Contact "A"	8 Copper Alloy(C7025)		Note. 1 0.12t
2	Metal Cover	Stainless Steel(STS304)		Note. 1 0.25t
1	Housing	8 Thermoplastic(HT3)	Black Color	UL94V-0

General Tolerance		Scale	Units	Sheet	TITLE	
Dimension	mm (°)	N/S	mm	1 of 1	HY20-AB0505 MMI Connector	
X	± 0.2	Date	2007.12.06		Customer Drawing	
X.X		Drawn	Design	Checked	Reviewed	Approved
X.XX		M.G. Son				
X.XXX						
ANGLE	± 3°	HJ&C HYUP JIN I&C CO., LTD.			SW No.	HY20-AB0505-A1.DWG
					DWG No.	HY20-AB0505-A1